Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) An adhesive material, for connecting a protuberant electrode of an electronic component to a terminal electrode of a circuit board for carrying said electronic component, the adhesive material containing at least one curable resin and inorganic particles, wherein as to the inorganic particles, their specific surface area S (m^2/g) satisfies Equation (1) below, their mean particle size D_1 (μm) and maximum particle size D_2 ~~(μ)~~ (μm) respectively satisfy Equations (2) and (3) below,

$$~~3~~ 11 < S \leq 17 \qquad (1)$$

$$D_1 \leq 5 \qquad (2)$$

$$D_2 \leq 0.5\,(h_1 + h_2) \qquad (3)$$

wherein ~~(wherein~~ h_1 represents the height of the protuberant electrode in the electronic component, and h_2 represents the height of the terminal electrode in the circuit ~~board),~~board,

~~and~~ the content of said inorganic particles is 10 to 60 ~~vol %.~~vol%, and

wherein the mean particle size D_1 of the inorganic particles further satisfies the Equation (4) below.

$$0.1(h_1 + h_2) \geq D_1 \qquad (4)$$

2-3. (Canceled)

4. (Currently Amended) The adhesive material according to ~~any of~~ Claim 1, further containing conductive particles having a mean particle size of 0.5 to 8.0 μm.

5. (Currently Amended) The adhesive material according to ~~any of~~ Claim 1, wherein the adhesive material has a coefficient of moisture absorption in a 85% RH, 85°C atmosphere is 1.5 wt % or less.

6. (Currently Amended) The adhesive material according to ~~any of~~ Claim 1, wherein the electronic component is a semiconductor element.

7. (New) The adhesive material according to Claim 1, wherein the specific surface area $S(m^2/g)$ of the inorganic particles satisfies the Equation below.

$$11 \leq S \leq 17$$